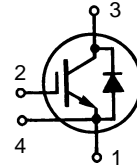


# IGBT with Diode

# IXSN 35N100U1

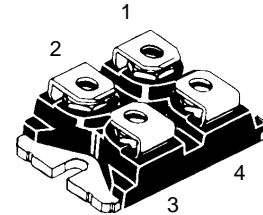
$V_{CES} = 1000 \text{ V}$   
 $I_{C25} = 38 \text{ A}$   
 $V_{CE(sat)} = 3.5 \text{ V}$

High Short Circuit SOA Capability



Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1000	V
$V_{CGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GE} = 1 \text{ M}\Omega$	1000	A
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$	38	A
$I_{C90}$	$T_C = 90^\circ\text{C}$	25	A
$I_{CM}$	$T_C = 25^\circ\text{C}$ , 1 ms	50	A
<b>SSOA (RBSOA)</b>	$V_{GE} = 15 \text{ V}$ , $T_{VJ} = 125^\circ\text{C}$ , $R_G = 22 \Omega$ Clamped inductive load, $L = 30 \mu\text{H}$	$I_{CM} = 50$ @ $0.8 V_{CES}$	A
<b><math>t_{SC}</math> (SCSOA)</b>	$V_{GE} = 15 \text{ V}$ , $V_{CE} = 0.6 \cdot V_{CES}$ , $T_J = 125^\circ\text{C}$ $R_G = 22 \Omega$ , non repetitive	10	$\mu\text{s}$
$P_c$	$T_C = 25^\circ\text{C}$	205	W
$V_{ISOL}$	50/60 Hz	2500	V~
	$I_{ISOL} \leq 1 \text{ mA}$	3000	V~
$T_J$		-40 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-40 ... +150	$^\circ\text{C}$
$M_d$	Mounting torque	1.5/13	Nm/lb.in.
	Terminal connection torque (M4)	1.5/13	Nm/lb.in.
<b>Weight</b>		30	g

miniBLOC, SOT-227 B



1 = Emitter, 3 = Collector  
2 = Gate, 4 = Kelvin Emitter

### Features

- International standard package miniBLOC (ISOTOP) compatible
- Isolation voltage 3000 V~
- 2nd generation HDMOS™ process
  - for high short circuit SOA
- Low  $V_{CE(sat)}$ 
  - for minimum on-state conduction losses
- MOS Gate turn-on
  - drive simplicity
- Fast Recovery Epitaxial Diode (FRED)
  - short  $t_{tr}$  and  $I_{RM}$
- Low collector-to-case capacitance (< 50 pF)
  - reduces RFI
- Low package inductance (< 10 nH)
  - easy to drive and to protect

### Applications

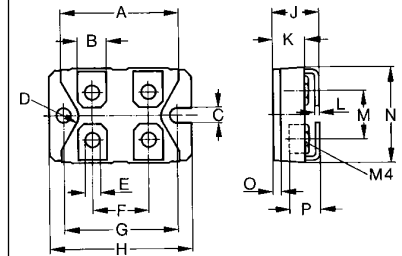
- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

### Advantages

- Space savings
- Easy to mount with 2 screws
- High power density

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C, unless otherwise specified)		
		min.	typ.	max.
$BV_{CES}$	$I_C = 6 \text{ mA}$ , $V_{GE} = 0 \text{ V}$	1000		V
$V_{GE(th)}$	$I_C = 10 \text{ mA}$ , $V_{CE} = V_{GE}$	5		8 V
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$		750 $\mu\text{A}$
		$T_J = 125^\circ\text{C}$		15 mA
$I_{GES}$	$V_{CE} = 0 \text{ V}$ , $V_{GE} = \pm 20 \text{ V}$			$\pm 500 \text{ nA}$
$V_{CE(sat)}$	$I_C = I_{C90}$ , $V_{GE} = 15 \text{ V}$			3.5 V

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$g_{fs}$	$I_C = I_{C90}$ ; $V_{CE} = 20\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$	10	20	S
$I_{C(on)}$	$V_{GE} = 15\text{ V}$		300	A
$C_{ies}$	$V_{CE} = 25\text{ V}$ , $V_{GE} = 0\text{ V}$ , $f = 1\text{ MHz}$		4.5	nF
$C_{oes}$			0.5	nF
$C_{res}$			0.09	nF
$Q_g$	$I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$ , $V_{CE} = 0.5 V_{CES}$		180	nC
$Q_{ge}$			45	nC
$Q_{gc}$			120	nC
$t_{d(on)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b> $I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$ , $V_{CE} = 0.6 \cdot V_{CES}$ , $R_{on} = 6.8\ \Omega$ , $R_{off} = 22\ \Omega$ Remarks: Switching times may increase for $V_{CE}$ (Clamp) $> 0.6 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$		80	ns
$t_{ri}$			150	ns
$t_{d(off)}$			800	ns
$t_{fi}$			2000	ns
$E_{on}$			3.2	mJ
$E_{off}$			6.8	mJ
$R_{thJC}$			0.61	K/W
$R_{thCK}$		0.05		K/W

**miniBLOC, SOT-227 B**


M4 screws (4x) supplied

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	31.5	31.7	1.241	1.249
B	7.8	8.2	0.307	0.323
C	4.0	-	0.158	-
D	4.1	4.3	0.162	0.169
E	4.1	4.3	0.162	0.169
F	14.9	15.1	0.587	0.595
G	30.1	30.3	1.186	1.193
H	38.0	38.2	1.497	1.505
J	11.8	12.2	0.465	0.481
K	8.9	9.1	0.351	0.359
L	0.75	0.85	0.030	0.033
M	12.6	12.8	0.496	0.504
N	25.2	25.4	0.993	1.001
O	1.95	2.05	0.077	0.081
P	-	5.0	-	0.197

**Reverse Diode (FRED)**

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_F$	$I_F = I_{C90}$ , $V_{GE} = 0\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$			2.3 V
$I_{RM}$	$I_F = I_{C90}$ , $V_{GE} = 0\text{ V}$ , $-di_F/dt = 480\text{ A}/\mu\text{s}$ $T_J = 125^\circ\text{C}$ , $V_R = 360\text{ V}$		33	A
$t_{tr}$		150		ns
$R_{thJC}$			0.7	K/W

 IXYS MOSFETs and IGBTs are covered by one of the following U.S.patents: 4,835,592 4,881,108 5,017,508 5,049,961 5,187,117 5,486,715  
 4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025

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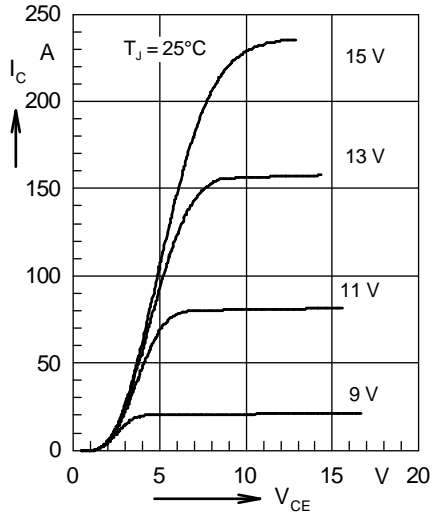


Fig. 1 Typ. output characteristics

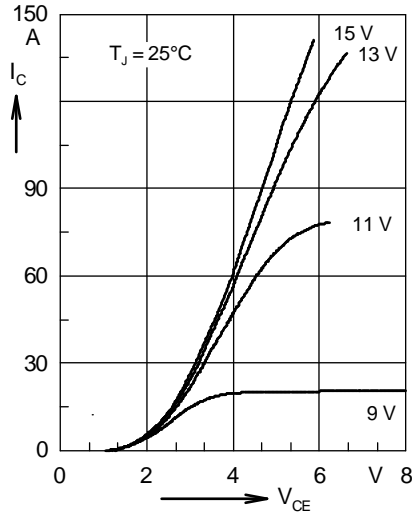


Fig. 2 Typ. output characteristics

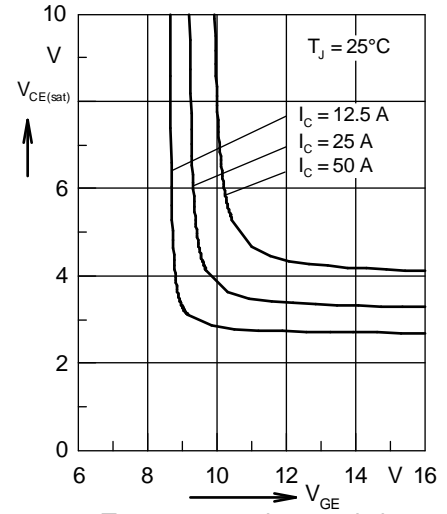


Fig. 3 Typ. on-state characteristics

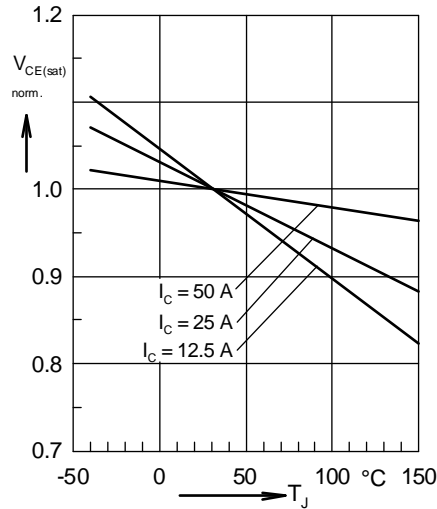


Fig. 4 Typ. temp. dependence of  $V_{CE(sat)}$

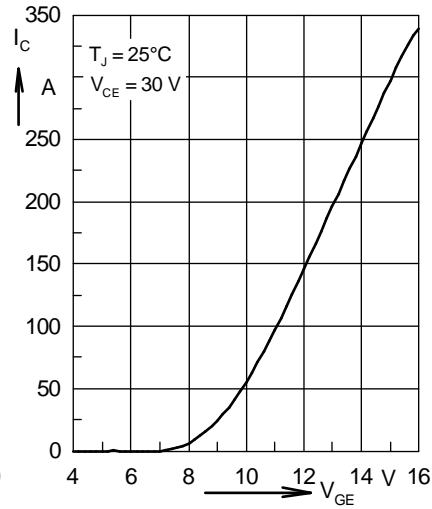


Fig. 5 Typ. transfer characteristics

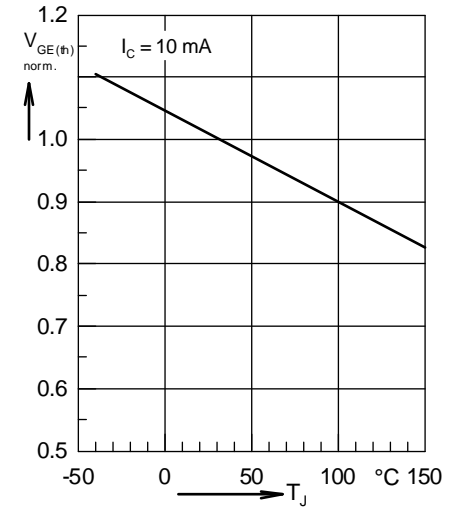


Fig. 6 Typ. temp. dependence of norm.  $V_{GE(th)}$

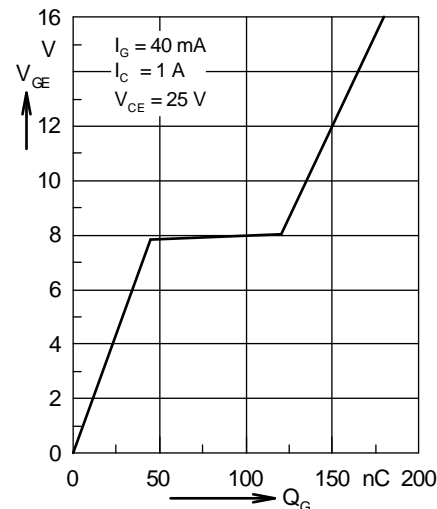


Fig. 7 Typ. turn-on gate charge characteristics,  $V_{GE} = f(Q_G)$

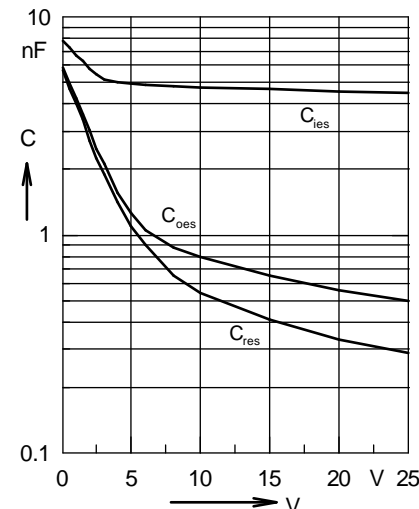


Fig. 8 Typ. capacitances

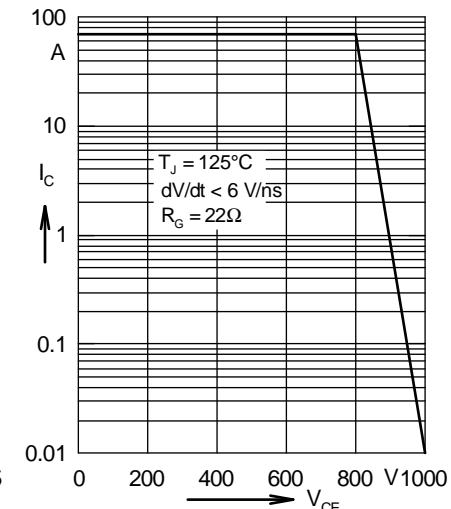


Fig. 9 Reverse biased safe operating area

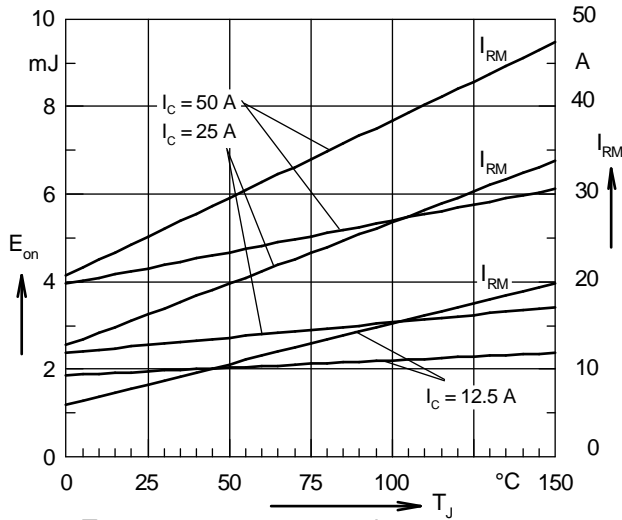


Fig. 10 Typ. turn-on energy per pulse

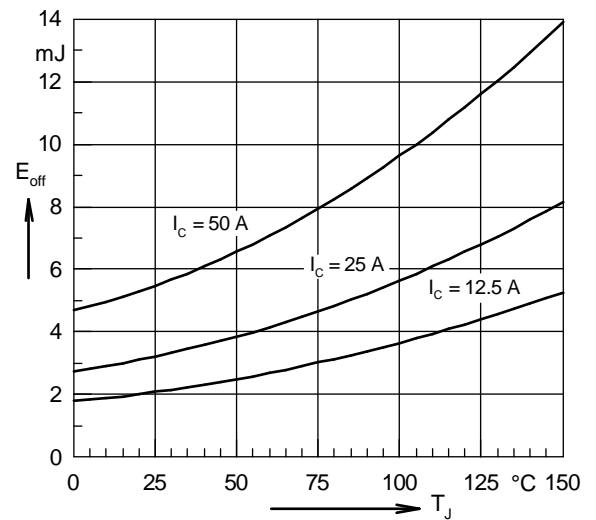


Fig. 11 Typ. turn-off energy per pulse

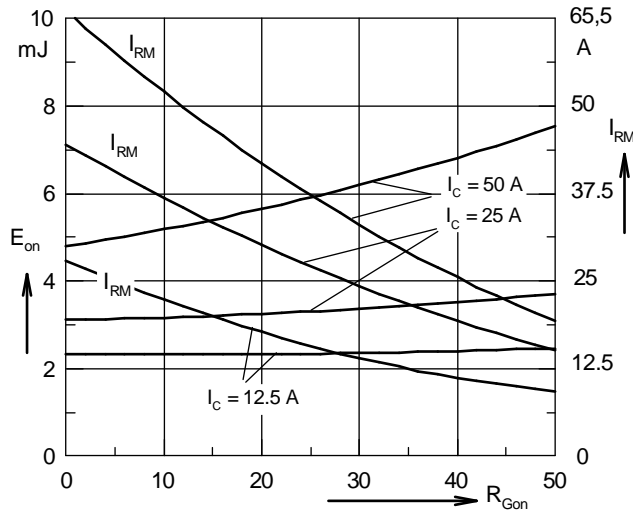


Fig. 12 Typ. turn-on energy per pulse

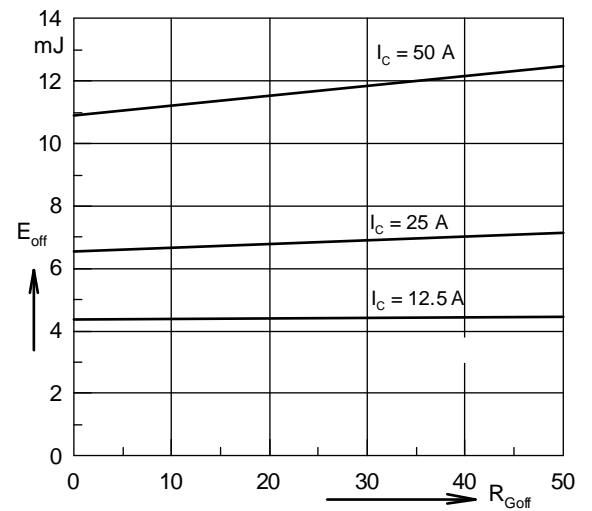


Fig. 13 Typ. turn-off energy per pulse

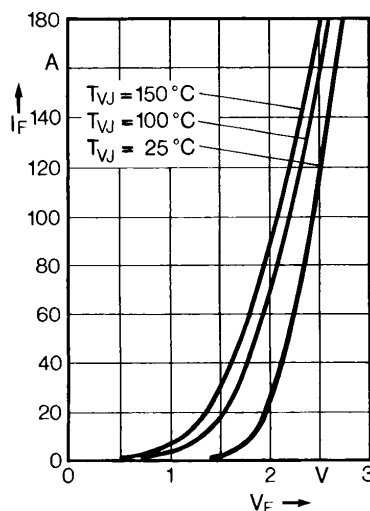


Fig. 14 Forward characteristic of reverse diode

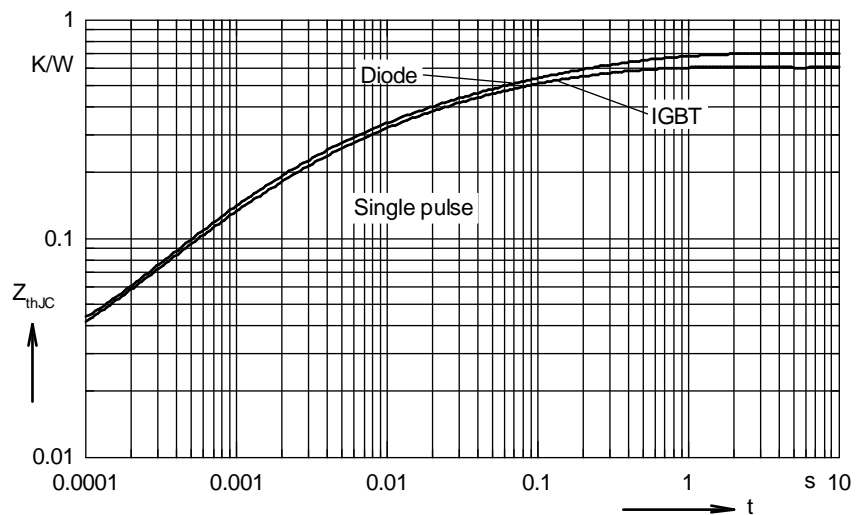


Fig. 15 Transient thermal resistance junction to case of IGBT and Diode

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